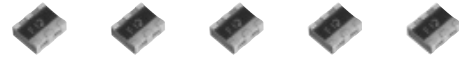


Ceramic Resonators, Chip Type

Type: **JN** (16 to 50 MHz)



■ Features

- Low Profile Type
- Designed for lead free soldering
- Wide Oscillation Frequency : 16 to 50 MHz
- High reliability against soldering heat and mechanical stress
- RoHS compliant

■ Recommended Applications

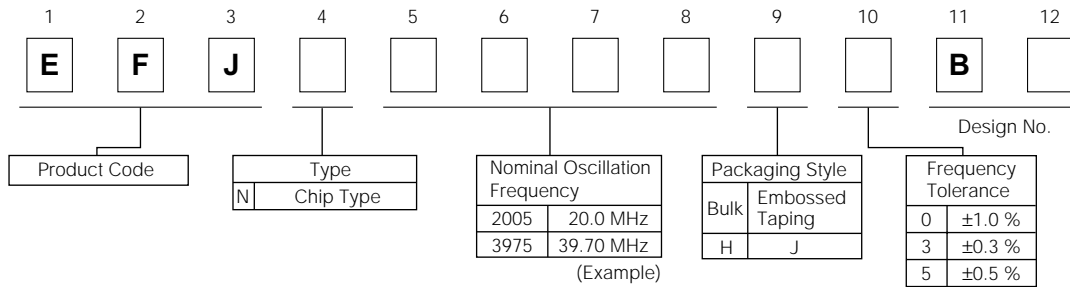
- Clock generator for microprocessors

■ Handling Precautions (See Page 201 to 202)

■ Packaging Specifications

See Page 200, 208

■ Explanation of Part Numbers



■ Ratings and Characteristics

Part Number		Oscillation Frequency (fo)	Loop Gain (G)	Temperature Characteristics
Bulk Pack	Embossed Taping			
EFJN1695H5B	EFJN1695J5B	16.93 MHz ±0.5 %	14 dB min.	Maximum frequency drift: ±0.2 %, -20 to 80 °C
EFJN2005H5B	EFJN2005J5B	20.00 MHz ±0.5 %		
EFJN2505H5B	EFJN2505J5B	25.00 MHz ±0.5 %	10 dB min.	
EFJN3205H5B	EFJN3205J5B	32.00 MHz ±0.5 %		
EFJN3385H5B	EFJN3385J5B	33.868 MHz ±0.5 %		
EFJN4005H5B	EFJN4005J5B	40.00 MHz ±0.5 %		

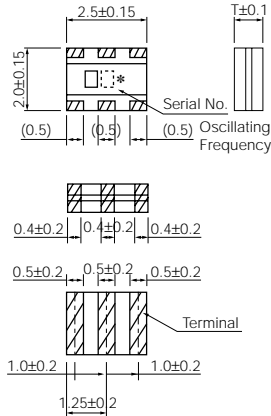
- Operating Temperature Range: -20 to 80 °C
- Frequency Drift : 0.2% max./10 years

Note : If customer used other frequency, please ask us separately.

■ Dimensions in mm (not to scale)

● Bulk

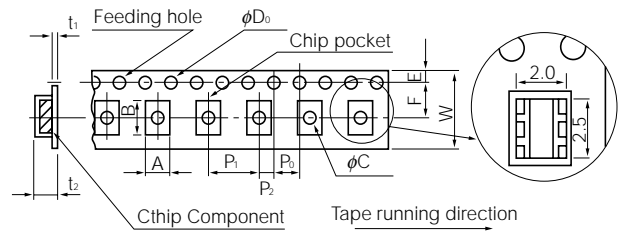
[Type JN] EFJN□□□□H□B



Thickness changes with Products
(40 MHz : 0.9 mm)

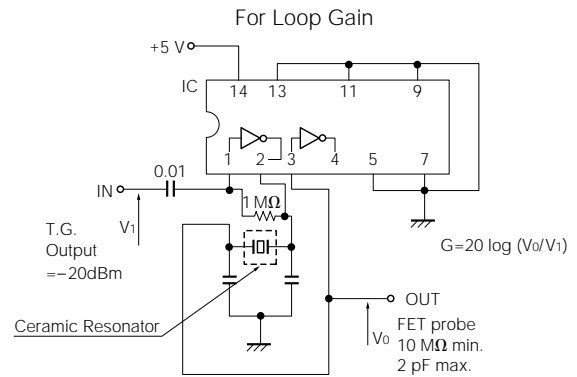
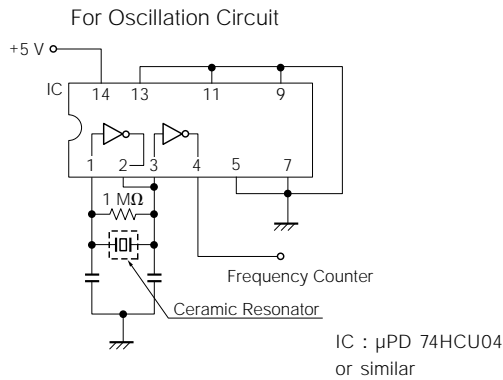
● Embossed Taping

[Type JN] EFJN□□□□□J□B



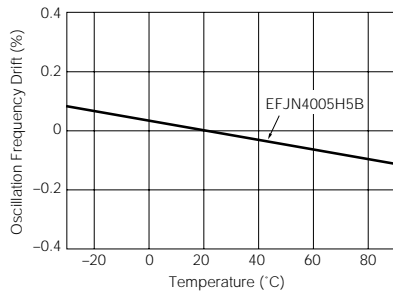
Dim. (mm)	A	B	W	F	E	P ₁
	2.3	2.8	8.0±0.2	3.5±0.1	1.75±0.1	4.0±0.1
Dim. (mm)	P ₂	P ₀	φD ₀	t ₁	t ₂	φC
	2.0±0.1	4.0±0.1	1.5 ^{+0.1} ₀	0.35	1.65	1.0

■ Test Circuits Diagram

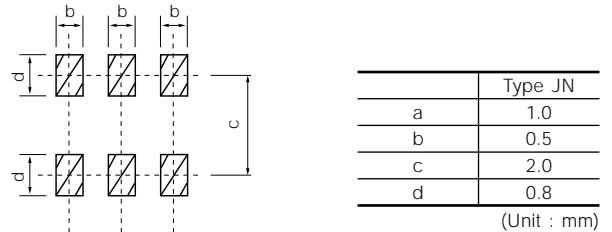


■ Typical Characteristics

Temperature Characteristics



■ Recommended Land Dimensions

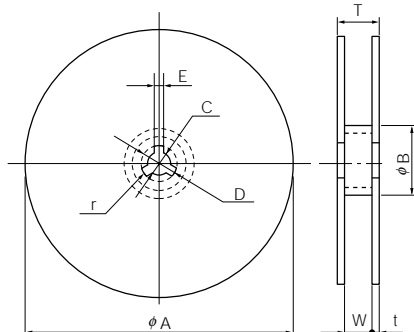


■ Packaging Specifications

● Standard Packing Quantity

Embossed Taping	Bulk
3000 pcs./reel	500 pcs./bag

● Dimensions for Reel in mm (not to scale)



Dim. (mm)	φA	φB	C	D	E
	180±5	60 min.	13±0.2	21±0.8	2.0±0.5
Dim. (mm)	W	T	t	r	
	9.0 ^{+1.0} _{-0.5}	14.0 max.	2.5 max.	1.0	